

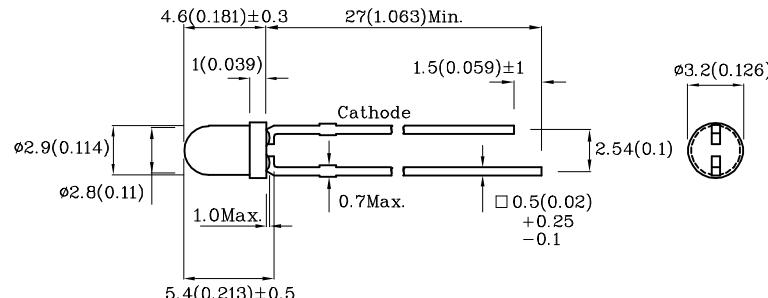
## Features

- Radial / Through hole package
- Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant

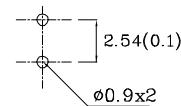


**ATTENTION**  
OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES

## Package Schematics



Recommended PCB Layout



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
3. Specifications are subject to change without notice.

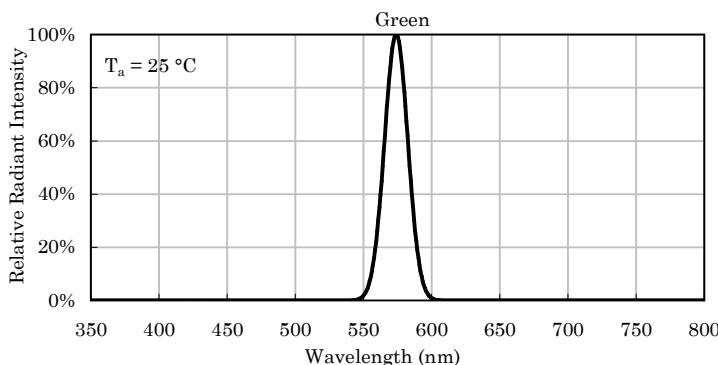
Absolute Maximum Ratings (TA=25°C)		Green (AlGaInP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	150	mA
Power Dissipation	P <sub>D</sub>	75	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>STG</sub>	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

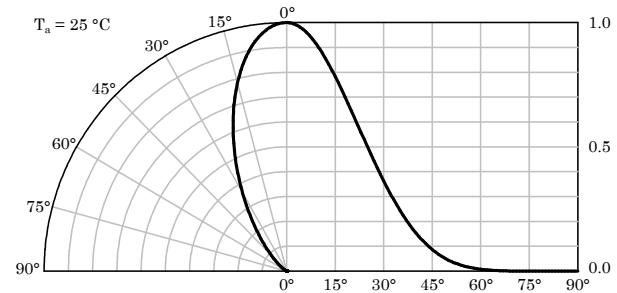
Operating Characteristics (TA=25°C)		Green (AlGaInP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =2mA)	V <sub>F</sub>	1.9	V
Forward Voltage (Max.) (I <sub>F</sub> =2mA)	V <sub>F</sub>	2.3	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	μA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I <sub>F</sub> =2mA)	λP	574*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =2mA)	λD	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =2mA)	△λ	20	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I <sub>F</sub> =2mA) mcd	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
XCVG11D	Green	AlGaInP	Green Diffused	4*	7*	574* 50°

\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

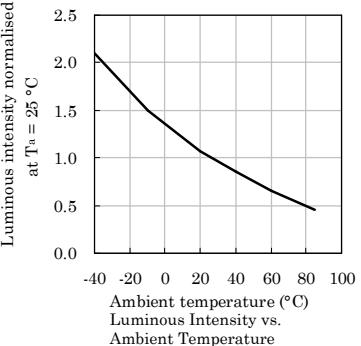
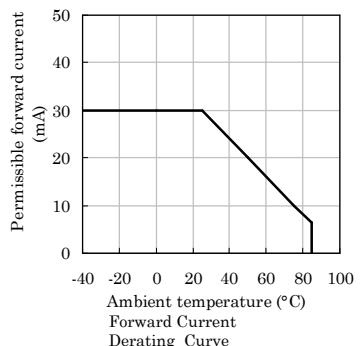
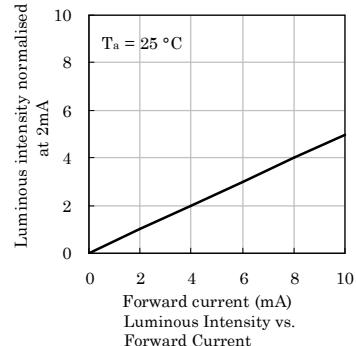
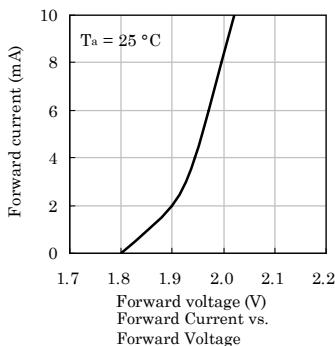


Relative Intensity Vs. CIE Wavelength

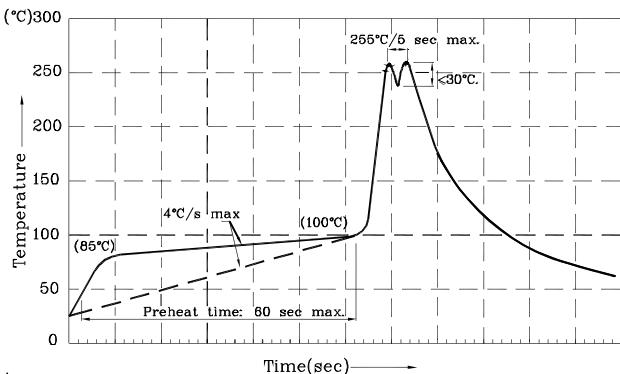


Spatial Distribution

## ❖ Green



### Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



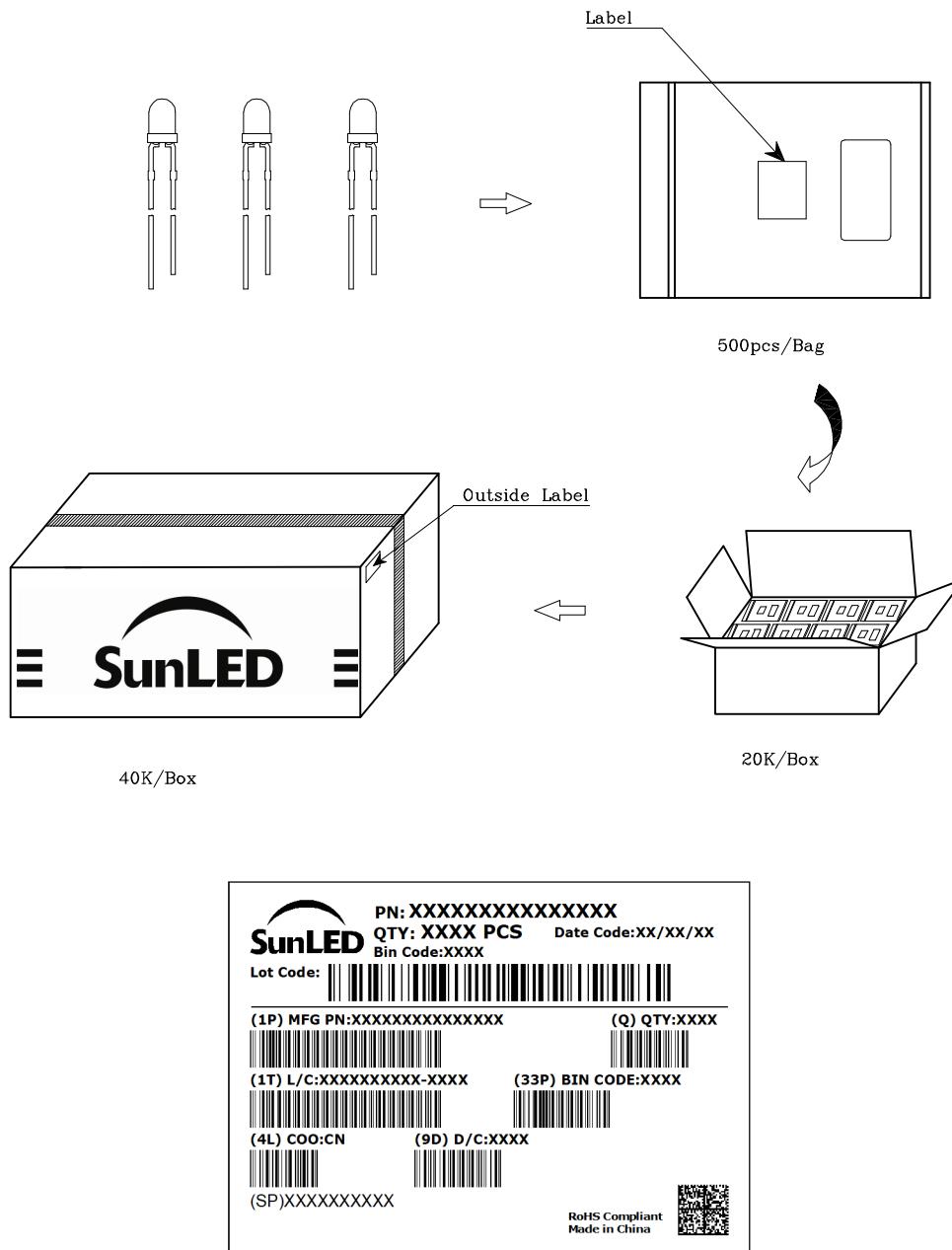
### Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength:  $\pm 1\text{nm}$
2. Luminous Intensity / Luminous Flux:  $\pm 15\%$
3. Forward Voltage:  $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**



**TERMS OF USE**

1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
2. Contents within this document are subject to improvement and enhancement changes without notice.
3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
5. The contents within this document may not be altered without prior consent by SunLED.
6. Additional technical notes are available at <https://www.SunLEDusa.com/TechnicalNotes.asp>